

WHAT IS CLAIMED IS:

1. A photocoupling device comprising:

an input section having a plurality of light emitting elements and lead terminals for supplying a drive current to the light emitting elements; and

an output section having a light receiving element opposed to light emitting faces of the light emitting elements and lead terminals for supplying a drive current to the light receiving element,

wherein the plurality of light emitting elements are connected in series.

2. The photocoupling device of claim 1, wherein the plurality of light emitting elements are connected in series via a plurality of headers.

3. The photocoupling device of claim 2, wherein at least one of the plurality of headers is provided with two light emitting elements.

4. The photocoupling device of claim 3, wherein structures of the two light emitting elements are different from each other.

5. The photocoupling device of claim 2, wherein at least one of the plurality of headers is a dummy header.

6. The photocoupling device of claim 5, wherein the dummy header is lead-cut from a lead frame inside a package which covers and protects the light emitting elements and the light receiving element.

7. The photocoupling device of claim 5, wherein the dummy header is lead-cut from a lead frame outside a package which covers and protects the light emitting elements and the light receiving element.

8. A method of manufacturing a photocoupling device comprising the steps of:

forming an input section having a plurality of light emitting elements and lead terminals for supplying a drive current to the light emitting elements and an output section having a light receiving element opposed to light emitting faces of the light emitting elements and lead terminals for supplying a drive current to the light receiving element;

connecting the plurality of light emitting elements in series via a plurality of headers, at least one of the plurality of headers being a dummy header; and

tie-bar cutting and lead cutting the dummy header at the same time.

9. The method of manufacturing a photocoupling device of claim 8, wherein a lead-cut portion of the dummy header is disposed in the vicinity of a tie-bar cut portion.

10. A method of manufacturing a photocoupling device, comprising the steps of:

forming an input section having a plurality of light emitting elements and lead terminals for supplying a drive current to the light emitting elements and an output section having a light receiving element opposed to light emitting faces of the light emitting elements and lead terminals for supplying a drive current to the light receiving element; and

connecting the plurality of light emitting elements in series via a plurality of headers, at least one of the plurality of headers being a dummy header,

wherein a lead frame is used in which the dummy header is connected to a header of another channel adjacent to the dummy header via a connecting member.

TOP SECRET

all
B1
C1

11
A: 102
B: 102
K2

A 10
B: 10

B: 10